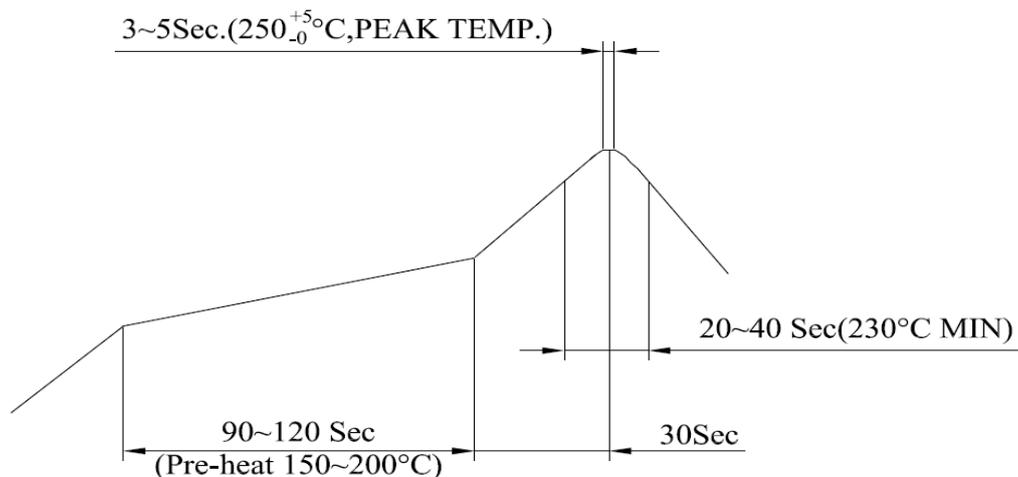


LEOCO CORPORATION	PRODUCTION SPECIFICATION	No.	S-17 -1259	REV	1
* 1259 SERIES CONNECTOR *					
This product specification contains the test method, the general performance and requirements for interconnection systems connector with 1259 series socket、header and terminal for high soldering temperature.					
1. Construction and dimensions shall be in accordance with the referenced drawings. 产品结构 and 尺寸依据所提的产品图面					
2. Characteristics 特性: Current rating 额定电流: 1 A AC, DC Voltage rating 额定电压: 125V AC,DC Temperature rating 额定温度: -40°C ~ +105°C Applicable wire 适用的线: conductor construction size #28 ~ #32 (Insulation O.D.0.9mm max.)					
3. Electrical performance 电气特性:					
Item	Description	Test Method & Condition	Requirement		
3-1	Contact Resistance 接触阻抗	It should be tested in accordance with method EIA-364-23	20 mΩ. max.		
3-2	Insulation Resistance 绝缘电阻	It should be tested in accordance with method EIA-364-21	100 MΩ. min.		
3-3	Dielectric Withstanding Voltage 耐电压	Unmated connector shall be tested in accordance with method EIA-364-20 When the AC 250V rms for 1 minute applied between adjacent contacts.	No evidence of break- Down and flashover		
4. Mechanical Performance 机械特性 :					
Item	Description	Test Method & Condition	Requirement		
4-1	Crimp tensile Strength 铆合张力强度	Pulling load shall be applied between correctly crimped terminal and wire at a constant speed. Pulling speed : 25 mm / minute	AWG #28: 1.0kgf min. AWG #30: 0.8kgf min. AWG #32: 0.3kgf min.		
4-2	Insertion & Withdrawal Force 插入力和拔出力	Insertion and Withdrawal connectors at the speed rate of 25 mm/minute.	Insertion Force: 0.22kgf max Withdrawal Force: 0.02kgf min		
4-3	Terminal Insertion Force 插入力	Insertion the crimped terminal into the housing at the speed rate of 25 mm / minute	0.5kgf max.		
4-4	Terminal/Housing Retention Force 保持力	The crimped terminal in a housing shall be pulled in a perpendicular at a constant speed of 25 mm/minute.	0.5kgf min.		

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4-5	Pin Retention Force Pin 针保持力	The end of a post shall be pushed in a perpendicular to base at a constant speed of 25 mm/minute.		0.2kgf min.			
4-6	Durability 耐久性	It should be tested in accordance with method EIA-364-09 Connector shall be subjected to 100 cycles Of insertion and withdrawal.		No defects. Contact resistance shall be 40 mΩ max.			
4-7	Vibration 振动性	The connector mated PCB shall be vibrated in accordance with method EIA-364-28 tested condition B. There shall be no current discontinuity longer than 1 microsecond during the test. Frequency:10~55~10 Hz/minute. Amplitude: 1.52mm Period: 2 hours for each direction.		No evidence of loosening of parts or electric discontinuity. Contact resistance less than twice of initial.			
5. Environmental Performance 环境特性 :							
Item	Description	Test Method & Condition		Requirement			
5-1	Humidity 耐湿性	The unmated connector shall be tested in accordance with method EIA-364-31 test procedure type I condition B. Temperature:40±2℃ Humidity:90-95% (RH), Period:96 hours		No Damage Contact Resistance: Less than twice of Initial. Insulation Resistance: to pass para 3-2 Dielectric Withstanding Voltage: to pass para 3-3.			
5-2	Salt Spray 盐雾测试	Connector shall be tested in accordance with method EIA-364-26 Temperature: 35±2℃ Density: 5% in weight. Period: 48 hours.		No damage. Contact resistance less than twice of initial.			
5-3	Solderability 着锡性	Connector termination ends shall be checked for solderability in accordance with method EIA-364-252. Solder temperature: 245±5℃ Immersion period: 5±0.5 sec.		No damage. Minimum: 95 % of immersed area.			
5-4	Resistance to Soldering Heat 耐高温焊接	Specimen shall be mounted on PCB. Solder temperature:260±5℃ Immersion period:5±0.5sec. When reflowing: Refer to paragraph 6.		No damage and deformation.			

6. Infrared Reflow Condition:



TEMPERATURE CONDITION GRAPH
TEMPERATURE ON BOARD PATTERN SIDE

NOTE : Please check the mount condition (reflow soldering condition) by your own devices beforehand, because the condition changes by the soldering devices,P.C. boards, and so on. No moisture treatment before reflow process.

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